



Features 特性

- Low Viscosity 低粘度
- Low Density 低密度
- Easy Handling 易操作
- High Reliability 高可靠性

Applications 产品应用

- Motor Potting 电机灌封
- Power Module 电源模块
- Charging Pile 充电桩
- ADAS 智能驾驶系统

Thermal TP0200LD 导热灌封胶是一种双组份加成型有机硅体系，具有导热率高，流动性好，低密度，优越的电气绝缘性能和阻燃性能。该产品适用于高功率电源及模块，电流/功率转换单元，高功率车载充电器及充电桩等高功率器件，可满足电气/电子封装领域对高导热性的要求，同时又能保持有机硅的理想特性。

Thermal TP0200LD thermally conductive potting compound is a two-component additional type silicone base with high thermal conductivity, good flowability, low density, superior electrical insulation and flame retardancy. It's suitable for high-power devices such as high-power supplies and modules, current/power conversion units, high power on-board chargers and charging piles. The product can meet the requirements for high thermal conductivity in the electrical/electronic packaging field and maintaining silicone polymer characteristics.

Property 特性	Typical Value 典型值	Unit 单位	Test Method 测试方法
Composition 主要成分	Silicone Filled with Thermal Powder 硅胶&导热粉体	—	—
Color 颜色	A – Gray 灰色 B – White 白色 Mix – Gray 灰色	Visual 目视	Visual 目视
Thermal Conductivity 导热系数	≥ 1.8	W/m·K	ASTM D5470
Viscosity 粘度 (A/B)	5000 ± 1000	mPa.s	ASTM D2196
Density 密度	2.0 ± 0.1	g/cm ³	ASTM D792
Hardness 硬度 (Shore A)	30 ± 10	—	ASTM D2240
Tacky-Free Time 表干时间	$\geq 30\text{min} @ \text{RT}$	—	—
Cure Time 固化时间	24H @ RT 15min @ 150°C	—	—
Temperature Range 耐温范围	-40 - 150	°C	—
Breakdown Voltage 击穿强度	≥ 8.0	KV/mm	ASTM D149
Flame Rating 阻燃等级	V-0	—	UL 94
RoHS Compliance 合规性	YES	—	—
Shelf Life 保存期	6	month	25±5°C, ≤50% RH

All technical information stated in this technical data have been confirmed that all the technical parameters are reliable after harsh testing and evaluation of the products. Before you use our products, please carefully evaluate and decide whether the product meets your requirement and you need to take all the risks and responsibilities to use.

此技术资料里所有陈述的技术信息，全部是基于本公司对自身产品在经过严格的测试评估后，证明各项技术参数指标是值得信赖的前提下编写的。在您使用我们公司产品之前，请充分评估该产品是否符合您的使用需求，您需要承担使用的全部风险和责任。